Product Bulletin

Document #:PB25588X
Issue Date:06 Sep 2023

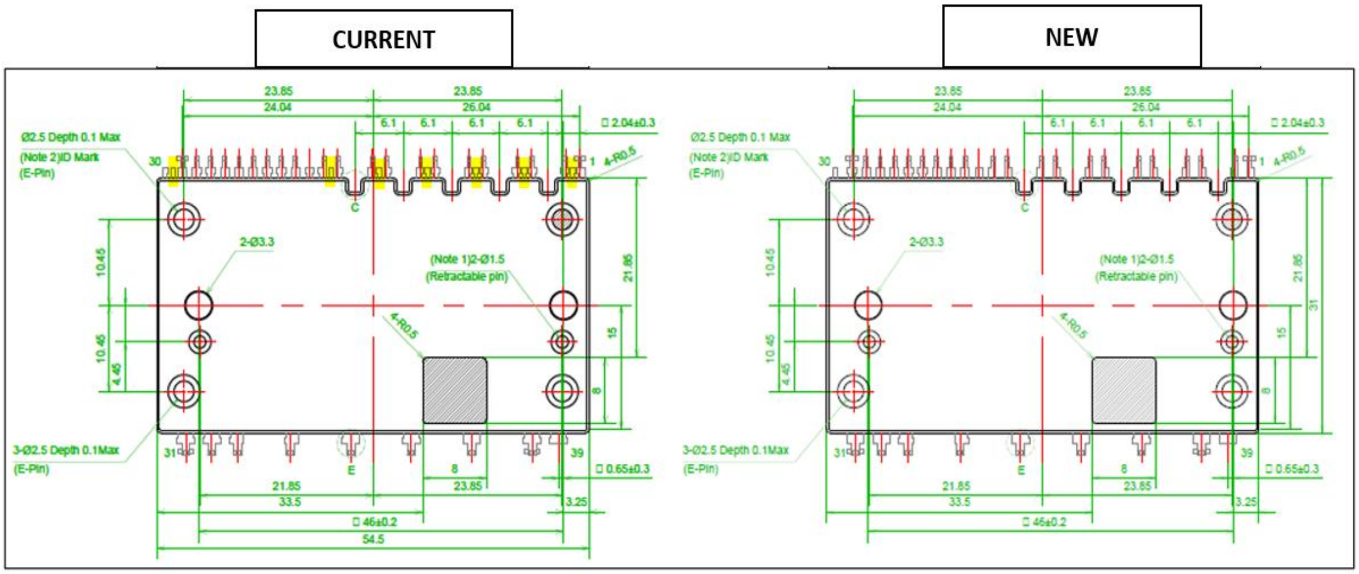
Title of Change:	Removal of dummy pin on Mini Dip packages
Effective date:	15 Nov 2023
Contact information:	Contact your local onsemi Sales Office or Anh.Vo@onsemi.com
Type of notification:	This Product Bulletin is for notification purposes only. onsemi will proceed with implementation of this change upon publication of this Product Bulletin.
Change Category:	Assembly Change
Change Sub-Category(s):	Datasheet/Product Doc change

Sites Affected:

onsemi Sites	**External Foundry/Subcon Sites**
onsemi Vietnam	None

Description and Purpose:

The purpose of this PB is to inform customers of the removal of dummy pins on Mini Dip packages and corresponding update to the package drawing.



List of Affected Standard Parts:

***Note**: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.*

NFAM2065L4B	NFAM2065L4BT	NFAM3065L4B
NFAM3065L4BT	NFAM3065L4BTL	NFAM5065L4B
NFAM5065L4BL	NFAM5065L4BBA	NFAM5065L4BTL
NFAM5065L4BT	NFAM3065L4BL	